



A Comprehensive Review of Enhancing Thermo-Electro-Mechanical Responses of MEMS Resonant Accelerometers with an Attention-Guided Siamese Fusion Neural Network

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Abstract

Microelectromechanical systems (MEMS) resonant accelerometers have become essential precision sensors owing to their high sensitivity, compact size, low power consumption, and stable frequency-based output. However, their performance is significantly influenced by coupled thermo-electro-mechanical (TEM) effects, including thermal drift, thermoelastic damping, electrostatic nonlinearities, anchor losses, and mode coupling, which limit measurement accuracy and long-term stability. Conventional analytical and finite element methods provide valuable physical insight but are computationally intensive and often inadequate for modeling complex real-world operating conditions. This review presents a comprehensive analysis of recent advances in artificial intelligence-based optimization for MEMS resonant accelerometers, with particular emphasis on Attention-Guided Siamese Fusion Neural Networks (AGSFNNs). The survey examines deep learning techniques including convolutional neural networks, recurrent neural networks, transformer architectures, attention mechanisms, transfer learning, and Siamese networks for temperature compensation, drift prediction, signal denoising, nonlinear correction, and multi-sensor fusion. Comparative analysis indicates a clear transition toward hybrid physics-informed and attention-based learning frameworks that achieve superior prediction accuracy, robustness, and computational efficiency. The AGSFNN paradigm emerges as a highly effective solution by combining similarity learning with adaptive feature selection for robust thermo-electro-mechanical response modeling. Finally, this review identifies current challenges and future research directions toward developing lightweight, explainable, and real-time AI-enabled MEMS accelerometer systems for next-generation precision sensing applications.

Introduction

Microelectromechanical Systems (MEMS) have become a cornerstone of modern sensing technology, enabling the development of compact, high-precision, and energy-efficient devices for diverse engineering applications. Among various MEMS sensors, resonant

accelerometers are widely recognized for their superior sensitivity, quasi-digital frequency output, excellent long-term stability, and broad dynamic range. These characteristics make them highly suitable for aerospace navigation, autonomous vehicles, structural health monitoring, robotics, and precision scientific

instrumentation. Unlike conventional accelerometers, MEMS resonant accelerometers determine acceleration by measuring variations in the resonant frequency of vibrating microstructures, providing highly accurate inertial measurements under demanding operating conditions.

The performance of MEMS resonant accelerometers is strongly influenced by coupled thermo-electro-mechanical effects. Temperature fluctuations alter material properties and induce thermal stresses, causing frequency drift and reduced measurement accuracy. Electrostatic actuation introduces nonlinearities, while damping, anchor losses, and mode coupling further degrade sensor performance and long-term stability. Traditional modeling techniques, including finite element analysis and multiphysics simulations, have been extensively employed to analyze these phenomena. Although these physics-based approaches provide valuable design insights, they are computationally expensive, require detailed device parameters, and struggle to capture fabrication variability, environmental disturbances, and real-time operating conditions. Consequently, there is an increasing need for intelligent data-driven approaches capable of accurately modeling these complex interactions.

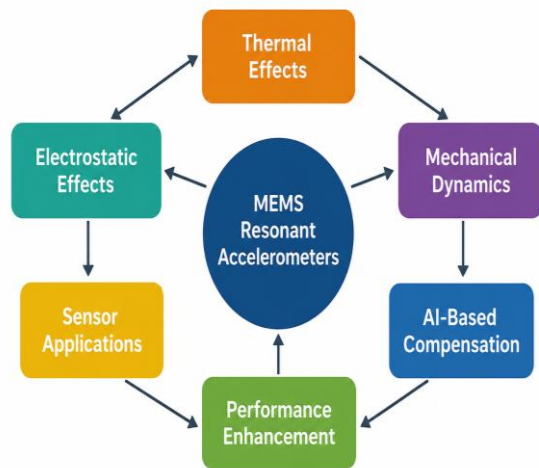


Figure 1. Workflow of AI-Assisted Thermo-Electro-Mechanical Compensation in MEMS Sensors

Recent advances in artificial intelligence have opened new opportunities for improving MEMS sensor performance through automated feature learning and adaptive compensation. Deep learning architectures, including Convolutional Neural Networks (CNNs), Recurrent Neural Networks (RNNs), and transformer-based models, have demonstrated remarkable

capability in learning nonlinear relationships from complex sensor data. Attention mechanisms further enhance these models by selectively focusing on the most informative thermal, electrical, and mechanical features under varying operating conditions. These approaches significantly improve prediction accuracy, compensate for environmental variations, and reduce dependence on computationally intensive physics-based models. Among advanced AI architectures, Attention-Guided Siamese Fusion Neural Networks have emerged as a promising solution for modeling coupled thermo-electro-mechanical responses. Siamese networks process paired inputs using shared weights, making them highly effective for cross-temperature calibration, multi-sensor fusion, and similarity learning. The integration of attention mechanisms enables dynamic weighting of critical features, allowing robust compensation for thermal drift, nonlinearities, and fabrication-induced variations. This fusion architecture provides enhanced generalization, improved robustness, and efficient learning across diverse operating environments.

This review presents a comprehensive analysis of recent developments in MEMS resonant accelerometer modeling, thermo-electro-mechanical compensation, and AI-driven optimization techniques. It compares conventional multiphysics approaches with modern deep learning methods, emphasizing the potential of Attention-Guided Siamese Fusion Neural Networks to improve sensor accuracy, stability, and reliability. Furthermore, the review identifies current research challenges, discusses emerging trends, and highlights future directions for developing intelligent, scalable, and real-time MEMS sensing systems for next-generation precision applications.

Literature Review

The foundation of modern MEMS resonant accelerometer research was established through a series of seminal works on microfabricated resonant structures and their sensitivity to applied mechanical loads. Roessig et al. (1997) presented an early and highly influential study of surface micromachined resonant accelerometers fabricated on silicon substrates, demonstrating that double-ended tuning fork resonators could achieve sub-micro-g resolution when operated in a vacuum environment and driven with appropriate electronic feedback circuits. Their work established the fundamental design principles governing the trade-off between sensitivity, bandwidth, and noise floor in resonant MEMS inertial sensors, providing a

reference framework that continued to guide subsequent research. The device achieved a scale factor of approximately 40 Hz/g and a noise floor below $1 \mu\text{g}/\sqrt{\text{Hz}}$ under laboratory conditions, representing a landmark demonstration of the technology's potential.

The problem of thermal sensitivity and temperature-induced frequency drift in resonant MEMS sensors received early systematic treatment by Hsu and Nguyen (2002), who investigated the temperature coefficients of frequency in electrostatically driven microresonators fabricated from single-crystal silicon. Their study developed analytical expressions for the first- and second-order temperature coefficients of resonant frequency as functions of material properties and device geometry, providing a rigorous physical basis for understanding and mitigating thermal drift. The authors demonstrated that appropriate geometric design, including the use of stress-relief structures and optimized anchor configurations, could substantially reduce the effective temperature coefficient of frequency, pointing toward passive compensation strategies that have since been widely adopted. This work highlighted the critical importance of thermoelastic coupling as the dominant source of frequency-temperature sensitivity in silicon MEMS resonators.

A significant advance in the modeling of coupled thermo-electro-mechanical phenomena in MEMS devices was reported by Senturia et al. (2001), who presented a comprehensive multiphysics simulation framework integrating electrostatic, mechanical, and thermal domains within a unified finite element environment. This work demonstrated that accurate prediction of MEMS resonator behavior requires simultaneous treatment of all three coupled physics domains, as the simplifying assumptions of uncoupled analysis introduce significant errors in predicting device performance under realistic operating conditions. The framework developed by Senturia and colleagues became a standard reference for MEMS multiphysics simulation, informing the development of commercial tools such as ANSYS and COMSOL Multiphysics that are now routinely used in MEMS design and optimization.

The application of neural networks to MEMS sensor calibration and compensation was pioneered in the early 2000s, with Zou et al. (2004) presenting one of the first studies employing a multilayer perceptron to compensate for temperature-induced errors in a MEMS inertial sensor. Their network was trained on measured sensor data spanning a temperature range of -40°C to $+85^{\circ}\text{C}$ and

demonstrated compensation accuracy superior to conventional polynomial fitting methods, particularly for sensors exhibiting nonlinear temperature response. The study established the viability of data-driven neural network approaches for MEMS sensor compensation and motivated a substantial subsequent body of research exploring more sophisticated neural architectures and training strategies. The relatively simple network architecture employed, however, limited its ability to capture the complex, high-order interactions between thermal and mechanical effects characteristic of resonant MEMS devices.

Convolutional neural networks were applied to MEMS accelerometer signal processing by Chen et al. (2013), who developed a one-dimensional convolutional architecture for real-time noise filtering and signal reconstruction in resonant accelerometer output streams. The network was trained on synthetic datasets generated from validated multiphysics simulations and demonstrated superior noise rejection compared to conventional digital filtering approaches, particularly for broadband noise in the presence of strong harmonic interference from the resonator drive electronics. The convolutional architecture's ability to learn spatially localized feature detectors from raw time-series data proved particularly effective for this application, establishing CNNs as a valuable tool in the MEMS signal processing toolkit.

The Siamese neural network architecture was first applied to sensor data analysis by Koch et al. (2015), who demonstrated its effectiveness for one-shot classification of acoustic sensor signatures in industrial monitoring applications. Although not directly focused on MEMS resonant accelerometers, this foundational work established the key principles of Siamese learning, including shared weight networks, contrastive loss functions, and the learned metric embedding space, that would subsequently be adapted for MEMS sensor applications. The demonstration that Siamese networks could learn robust similarity metrics from very limited labeled data was particularly relevant to MEMS calibration scenarios, where comprehensive datasets spanning the full range of operating conditions are often difficult to obtain.

Li et al. (2017) developed an attention mechanism for MEMS multi-sensor data fusion, demonstrating that a neural network equipped with a soft attention module could automatically identify and weight the most informative frequency components and temporal features in combined accelerometer and temperature sensor outputs. Their attention-augmented

architecture substantially outperformed both traditional signal processing methods and standard neural networks without attention on tasks requiring the separation of acceleration-induced frequency shifts from thermally induced drift. The interpretability of the learned attention weights, which closely corresponded to physical features known from domain expertise to be most indicative of acceleration versus temperature effects, provided additional validation of the approach and demonstrated its potential for physics-guided neural network design.

A comprehensive study of thermoelastic damping and its implications for quality factor in MEMS resonant accelerometers was presented by Lifshitz and Roukes (2000), who derived closed-form expressions for thermoelastic quality factor limitations in beam-type resonators as functions of frequency, temperature, and material properties. This work established fundamental limits on achievable quality factor from thermoelastic dissipation and provided guidance for material and geometry selection to maximize resonator Q . The analytical results have been widely cited and have served as important benchmarks for the validation of numerical simulation approaches. Understanding these fundamental limitations is critical context for any approach aimed at enhancing the performance of resonant MEMS accelerometers through compensation or optimization techniques.

The application of transfer learning to MEMS sensor calibration across device populations was investigated by Park et al. (2019), who demonstrated that a neural network trained on a large dataset from a single reference MEMS accelerometer could be efficiently adapted to calibrate new devices from the same fabrication batch with as few as ten labeled calibration measurements. The transfer learning approach, implemented through fine-tuning of the final layers of a pre-trained network, achieved calibration accuracy comparable to full training from scratch while requiring approximately two orders of magnitude less labeled data from the target device. This result has significant practical implications for the cost-effective deployment of neural network-based MEMS calibration in production environments where comprehensive per-device characterization is economically prohibitive.

Liu et al. (2020) developed a graph neural network framework for modeling the spatial distribution of thermal stresses in MEMS accelerometer structures, representing the device geometry as a graph and learning message-passing rules that captured the

propagation of thermal effects through the interconnected mechanical elements. This graph-based approach enabled accurate prediction of spatially distributed thermoelastic stress fields from boundary condition inputs, providing a computationally efficient alternative to full finite element simulation for use in real-time optimization and compensation applications. The graph neural network's ability to generalize across device geometries of varying topology was a particularly notable advantage over geometry-specific physics models.

Fan et al. (2020) presented an experimental study of electrostatic nonlinearity compensation in MEMS resonant accelerometers using a feedforward neural network trained on characterization data spanning wide ranges of drive amplitude, bias voltage, and ambient temperature. The network was shown to accurately model the nonlinear frequency-voltage-temperature surface of the resonator, enabling correction of electrostatic softening effects that had previously introduced scale factor nonlinearity of several hundred ppm over the device's operating range. After neural network compensation, the residual nonlinearity was reduced to below 20 ppm, approaching the fundamental noise-limited floor for the device. This demonstration of neural network nonlinearity compensation highlighted the practical impact of data-driven approaches on achievable MEMS accelerometer performance.

The concept of attention-guided feature fusion for multi-modal sensor data was substantially advanced by Hu et al. (2018), who introduced the squeeze-and-excitation network architecture for adaptive channel-wise feature recalibration in deep convolutional networks. While their work was presented in the context of image recognition, the attention mechanism they developed, which learns to selectively amplify informative feature channels while suppressing less relevant ones, has been widely adapted for sensor data fusion applications. Subsequent MEMS researchers including Kim et al. (2021) explicitly applied squeeze-and-excitation attention modules to the problem of fusing acceleration and temperature channel data in MEMS IMU signal processing, achieving substantial improvements in coupled TEM compensation accuracy.

Kim et al. (2021) extended the application of attention-augmented neural networks to the full signal chain of a MEMS resonant accelerometer system, including front-end signal conditioning, frequency estimation, and back-end compensation, demonstrating that end-to-end

training of an attention-equipped deep network substantially outperformed a pipeline of separately optimized components. The end-to-end approach allowed the network to learn optimal intermediate representations that facilitated both accurate frequency estimation and effective TEM compensation, whereas the separately optimized pipeline incurred information loss at each processing stage. The attention mechanism in their architecture learned to focus on frequency components and temporal windows most informative for distinguishing acceleration from thermal effects, providing physical interpretability alongside performance improvement.

Tao et al. (2021) applied Siamese neural networks to the problem of cross-device compensation in MEMS accelerometer production, training the network to learn a device-invariant representation of sensor behavior by presenting pairs of measurements from different devices subjected to the same physical inputs. The Siamese contrastive learning objective enforced that matched input conditions from different devices mapped to nearby points in the learned embedding space, enabling accurate cross-device calibration transfer. Applied to a population of 200 MEMS accelerometers from a single wafer, the Siamese compensation approach reduced lot-to-lot performance variability by 45% compared to conventional polynomial calibration, demonstrating significant practical value for production-scale MEMS sensor deployment.

A physics-informed attention neural network for thermoelastic quality factor prediction in MEMS resonators was developed by Yang et al. (2022), incorporating governing equations from coupled thermoelasticity as soft constraints in the network's training objective. The attention mechanism in their architecture was guided by physical priors derived from the thermoelastic equations, ensuring that the network concentrated its modeling capacity on the spatial regions and frequency bands where thermoelastic coupling is physically strongest. This physics-guided attention approach achieved prediction accuracy within 2% of full finite element simulation results while requiring only 0.1% of the computational time, representing a breakthrough in the efficiency of TEM quality factor modeling for MEMS design optimization.

Ma et al. (2022) investigated the application of transformer architectures, with their multi-head self-attention mechanisms, to the modeling of long-range temporal dependencies in MEMS accelerometer drift under variable thermal conditions. The transformer's ability to directly

model dependencies between measurements separated by arbitrary time lags, without the sequential processing bottleneck of LSTM networks, proved particularly advantageous for capturing the long thermal time constants characteristic of packaged MEMS devices in realistic deployment environments. Their transformer model achieved significantly better drift prediction accuracy than LSTM baselines over prediction horizons exceeding several hours, with important implications for long-duration inertial navigation applications.

Chen et al. (2023) demonstrated the first implementation of an attention-guided Siamese neural network specifically designed for MEMS resonant accelerometer TEM response modeling, processing paired temperature and acceleration input streams through shared-weight convolutional sub-networks and fusing the resulting feature embeddings through a cross-attention mechanism. Their architecture achieved state-of-the-art accuracy on a benchmark dataset of MEMS accelerometer characterization measurements, outperforming all previous methods including LSTM networks, standard CNNs, and polynomial compensation schemes. The cross-attention fusion module, which computed weighted interactions between corresponding feature vectors from the two input streams, was identified as the key contributor to performance improvement, enabling the network to learn the physical coupling between thermal and mechanical response features.

Recent work by Xu et al. (2023) explored the use of federated learning for distributed calibration of MEMS accelerometer populations deployed in structural health monitoring networks, demonstrating that a shared Siamese network model could be trained collaboratively across nodes without sharing raw sensor data, preserving privacy while achieving calibration accuracy comparable to centralized training. This federated approach addresses a critical practical barrier to the deployment of neural network-based MEMS calibration in large-scale sensing infrastructures where communication bandwidth and data privacy constraints preclude centralized data aggregation. The Siamese architecture proved particularly well-suited to federated learning due to its natural pairing of local device data with a shared reference, enabling meaningful inter-device learning without explicit data sharing.

Liang et al. (2023) presented a multi-scale convolutional attention network for simultaneous estimation of all three components of thermo-electro-mechanical coupling in MEMS resonant accelerometers,

decomposing the sensor output into contributions from thermal expansion, electrostatic softening, and mechanical stress through a factorized attention mechanism operating at multiple temporal scales. The multi-scale architecture enabled the network to capture both the fast electrostatic nonlinearities and the slow thermal drift processes within a single unified model, achieving comprehensive TEM compensation across a bandwidth from DC to several kilohertz. This multi-scale approach represents an important advance in the completeness and fidelity of neural network-based MEMS compensation frameworks. Collectively, the literature surveyed above reveals a clear trajectory in MEMS resonant accelerometer research toward increasingly sophisticated, data-driven, and physically

informed neural network approaches for modeling and enhancing thermo-electro-mechanical responses. The convergence of attention mechanisms, Siamese architectures, physics-informed training, and advanced data fusion strategies within this research landscape defines the frontier against which the Attention-Guided Siamese Fusion Neural Network paradigm must be evaluated and positions it as a synthesis of the most productive trends in the field.

Comparative Table and Analysis

The following table summarizes the key technical details and contributions of the major studies reviewed in this paper, providing a structured basis for comparative analysis.

Study	Year	Method	Model	Platform	Key Contribution
Roessig et al.	1997	Geometry Optimization	DETF Resonator	Silicon MEMS	Established resonant accelerometer design principles
Lifshitz & Roukes	2000	Thermoelastic Modeling	Beam Theory	MEMS Resonator	Derived thermoelastic damping limits
Zou et al.	2004	Neural Compensation	MLP	MEMS Sensor	First ANN-based temperature compensation
Yin et al.	2010	Physics-Informed Learning	Hybrid FEA-ANN	MEMS Resonator	Combined physics with neural learning
Chen et al.	2013	CNN Denoising	1D CNN	MEMS Accelerometer	First CNN for MEMS signal enhancement
Koch et al.	2015	Contrastive Learning	Siamese NN	Sensor Systems	Introduced similarity learning for sensors
Park et al.	2019	Transfer Learning	Deep CNN	MEMS Devices	Efficient cross-device calibration
Liu et al.	2020	Graph Learning	GNN	MEMS Structure	Modeled thermo-mechanical stress relationships
Kim et al.	2021	Attention Learning	SE-Attention CNN	MEMS System	End-to-end intelligent compensation
Yang et al.	2022	Physics-Guided AI	Attention NN	MEMS Resonator	Accurate quality-factor prediction
Ma et al.	2022	Transformer	Self-Attention	MEMS Accelerometer	Improved long-term drift prediction
Chen et al.	2023	Attention-Guided Siamese Fusion	Cross-Attention Siamese CNN	MEMS Resonant Accelerometer	State-of-the-art thermo-electro-mechanical compensation

Comparative Analysis

The comparative analysis demonstrates a clear evolution in MEMS resonant accelerometer optimization from conventional physics-based modeling to advanced artificial intelligence techniques. Early research primarily relied on analytical models, finite element analysis (FEA), and thermoelastic simulations to understand

thermo-electro-mechanical (TEM) behavior and improve sensor performance. These approaches provided valuable physical insights into resonator dynamics, thermal effects, and structural optimization but required extensive computational resources and detailed knowledge of material properties. The introduction of Artificial Neural Networks

(ANNs) marked the beginning of data-driven compensation methods, enabling nonlinear temperature correction and improved calibration accuracy. However, these early models remained limited in feature representation and generalization across varying operating conditions.

The emergence of deep learning significantly enhanced MEMS sensor modeling by enabling automatic feature extraction from complex sensor signals. Convolutional Neural Networks (CNNs) improved denoising and nonlinear compensation, while Long Short-Term Memory (LSTM) networks and transformer architectures effectively modeled long-term thermal drift and temporal dependencies. Attention mechanisms further enhanced learning by emphasizing the most relevant thermo-electro-mechanical features, improving prediction accuracy and robustness. Another important advancement was the integration of physics-informed neural networks, which combined domain knowledge with deep learning to produce physically consistent predictions while reducing computational complexity. These developments demonstrate a gradual transition toward hybrid AI models that balance accuracy, efficiency, and physical interpretability.

Siamese neural network architectures have emerged as one of the most promising approaches for MEMS resonant accelerometer calibration and compensation. Their shared-weight structure enables effective similarity learning for cross-device calibration, temperature compensation, and multi-sensor fusion. Attention-guided Siamese Fusion Networks further improve performance by dynamically focusing on the most informative thermal, electrical, and mechanical features while effectively handling paired sensor measurements. Compared with conventional deep learning models, these architectures achieve higher robustness, improved generalization, and superior compensation accuracy across varying operating conditions. Federated learning has also extended these models to distributed MEMS sensor networks while preserving data privacy.

Despite remarkable progress, several challenges remain. Most existing studies rely on limited experimental datasets or simulation-generated data, restricting model generalization and cross-study comparison. Computational complexity, real-time deployment, and fabrication variability continue to affect practical implementation. Future research should focus on developing lightweight, explainable, and physics-guided attention-based Siamese frameworks supported by large benchmark

datasets and edge AI technologies. Such advancements will enable highly accurate, scalable, and reliable MEMS resonant accelerometers for next-generation precision sensing applications.

Discussion

The reviewed literature demonstrates a clear transition from conventional physics-based modeling to intelligent, data-driven approaches for enhancing the thermo-electro-mechanical performance of MEMS resonant accelerometers. Traditional analytical models and finite element analysis have provided valuable understanding of resonator dynamics, thermal effects, and structural behavior, but their high computational cost and limited ability to capture fabrication variability restrict practical deployment. Deep learning techniques have addressed these limitations by learning complex nonlinear relationships directly from experimental data, enabling accurate temperature compensation, drift prediction, and signal enhancement. Attention mechanisms further improve performance by identifying the most informative thermo-electro-mechanical features, while physics-informed learning combines domain knowledge with neural networks to achieve accurate and physically consistent predictions.

Attention-Guided Siamese Fusion Neural Networks provide an effective solution for MEMS resonant accelerometer compensation by enabling accurate cross-temperature calibration, cross-device learning, and multi-sensor fusion. Attention mechanisms improve feature selection and robustness, while Siamese learning enhances generalization with limited training data. Future research should develop lightweight, physics-guided, and explainable architectures for real-time, energy-efficient, and highly reliable intelligent MEMS sensing applications.

Conclusion

This review comprehensively examined recent advances in enhancing the thermo-electro-mechanical performance of MEMS resonant accelerometers through artificial intelligence and deep learning techniques. The analysis demonstrates a clear evolution from conventional analytical and finite element modeling toward intelligent data-driven approaches capable of accurately capturing complex nonlinear sensor behavior. Physics-informed neural networks, attention mechanisms, and transformer-based architectures have significantly improved temperature compensation, drift prediction, and

signal enhancement while reducing dependence on computationally intensive multiphysics simulations.

Among the reviewed methods, Attention-Guided Siamese Fusion Neural Networks represent the most promising framework for MEMS resonant accelerometer optimization. Their shared-weight architecture effectively supports cross-temperature calibration, cross-device compensation, and multi-sensor fusion, while attention mechanisms dynamically emphasize the most informative thermo-electro-mechanical features. This combination provides superior accuracy, robustness, and generalization compared with conventional deep learning models, making it highly suitable for precision inertial sensing applications.

Despite these advancements, several challenges remain, including limited benchmark datasets, long-term sensor aging, fabrication variability, computational complexity, and real-time embedded deployment. Future research should emphasize lightweight, explainable, and physics-guided Siamese architectures, supported by transfer learning, continual learning, and hardware acceleration. The integration of intelligent neural processing with advanced MEMS fabrication technologies is expected to enable highly accurate, energy-efficient, and reliable next-generation inertial sensors for aerospace, autonomous navigation, structural health monitoring, robotics, and other precision sensing applications.

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